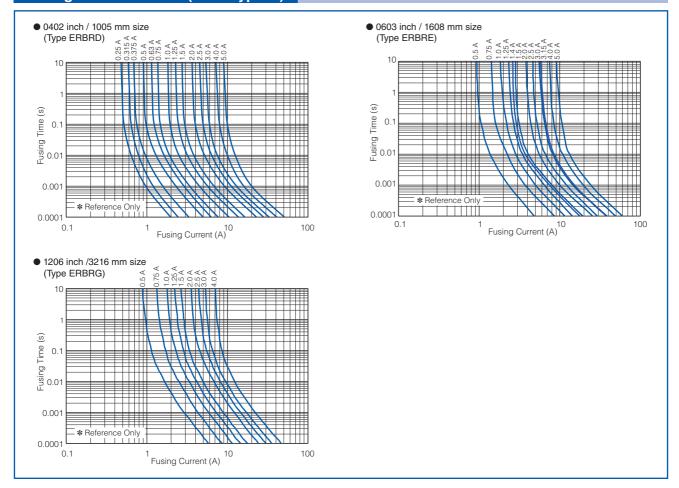


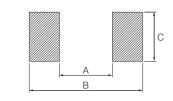
# Fusing Characteristics (25 °C typical)



## **Perfomance**

Test Item	Performance Requirements	Test Conditions
Resistance	Within Specified Tolerance	25 °C
Resistance to Soldering Heat	±10 %	260 °C±5 °C, 10 s
Rapid Change of Temperature	±10 %	-40 °C (30 min.) / +125 °C (30 min.), 5 cycles
Damp Heat, Steady State	±10 %	60 °C, 90 % to 95 %RH, 1000 h (no load)
Load Life in Humidity	±10 %	60 °C, 90 % to 95 %RH, Load: 70 % rated current, 1000 h
Endurance at 70 °C	±10 %	70 °C , Load: 70 % rated current, 1000 h

## **Recommended Soldering Conditions**



Part No.	Dimensions (mm)			
(inch size)	А	В	С	
ERBRD(0402)	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6	
ERBRE(0603)	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0	
ERBRG(1206)	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8	



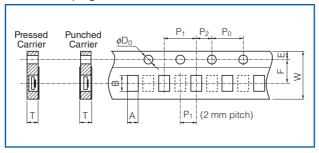
## **Packaging Methods**

### Standard Quantity

Part No.	inch size	Kind of Taping	Pitch (P <sub>1</sub> )	Quantity
ERBRD	0402	Pressed Carrier Taping	2 mm	10,000 pcs./ reel
ERBRE	0603	Dunched Carrier Taning	4 mm	5 000 pag / rool
ERBRG	1206	Punched Carrier Taping	4 mm	5,000 pcs./ reel

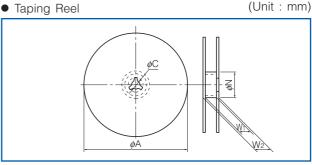
(Unit: mm)

### Carrier Taping



Part No.	А	В	W	F	Е
ERBRD	0.68 <sup>±0.10</sup>	1.20 <sup>±0.10</sup>			
ERBRE	1.10 <sup>±0.10</sup>	1.90 <sup>±0.10</sup>	8.00 <sup>±0.20</sup>	3.50 <sup>±0.05</sup>	1.75 <sup>±0.10</sup>
ERBRG	2.00 <sup>±0.15</sup>	3.60 <sup>±0.20</sup>			
Part No.	D,	D <sub>o</sub>	D <sub>o</sub>	۵₽۵	т
Part No.	P <sub>1</sub>	P <sub>2</sub>	P <sub>0</sub>	<b>ø</b> D₀	Т
Part No.	P <sub>1</sub> 2.00 <sup>±0.10</sup>			,	T 0.67 <sup>±0.07</sup>
		P <sub>2</sub> 2.00 <sup>±0.05</sup>	P <sub>0</sub> 4.00 <sup>±0.10</sup>	φD <sub>0</sub> 1.50 <sup>+0.10</sup>	T 0.67 <sup>±0.07</sup> 0.78 <sup>±0.07</sup> 0.84 <sup>±0.07</sup>

### Taping Reel

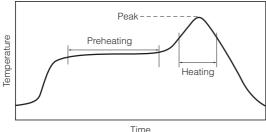


Part No.	φA	φN	φC	W <sub>1</sub>	W <sub>2</sub>
ERBRD ERBRE ERBRG	180.0-1.5	60 +1.0	13.0 <sup>±0.2</sup>	9.0 +1.0	11.4 <sup>±1.0</sup>

## **Recommended Soldering Conditions**

Recommendations and precautions are described below.

- Recommended soldering conditions for reflow
- Reflow soldering shall be performed a maximum of two times.
- · Please contact us for additional information when used in conditions other than those specified.
- Please measure the temperature of the terminals and study every kind of solder and printed circuit board for solderability before actual use.



For soldering (Example: Sn/Pb)

	Temperature	Time
Preheating	140 °C to 160 °C	60 s to 120 s
Main heating	Above 200 °C	30 s to 40 s
Peak	235 ± 5 °C	max. 10 s

For lead-free soldering (Example: Sn/Ag/Cu)

	Temperature	Time
Preheating	150 °C to 180 °C	60 s to 120 s
Main heating	Above 230 °C	30 s to 40 s
Peak	max. 260 °C	max. 10 s

Recommended soldering conditions for flow

	For soldering		For lead-free soldering		
	Temperature	Time	Temperature	Time	
Preheating	140 °C to 180 °C	60 s to 120 s	150 °C to 180 °C	60 s to 120 s	
Soldering	245 ± 5 °C	20 s to 30 s	max. 260 °C	max. 10 s	

<Repair with hand soldering>

- Preheat with a blast of hot air or similar method. Use a soldering iron with a tip temperature of 350 °C or less. Solder each electrode for 3 seconds or less.
- Never touch this product with the tip of a soldering iron.